# 1735446-9 - ACTIVE

TE Internal #: 1735446-9 PCB Mount Header, Vertical, Wire-to-Board, 9 Position, 2 mm [.079 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, Signal, Natural

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Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 2.0 mm Headers



Connector System: Wire-to-Board

Number of Positions: 9

Number of Rows: 1

Centerline (Pitch): 2 mm [.079 in ]

PCB Mount Orientation: Vertical

All AMP HPI 2.0 mm Headers (206)

### Features

#### Product Type Features

Connector SystemWire-to-BoardHeader TypePartially Shrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Connector Contact Load Condition	Fully Loaded
Number of Positions	9
Number of Rows	1
PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
Contact Mating Area Length	3.35 mm[.131 in]
Mating Square Post Dimension	.5 mm[.02 in]

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PCB Contact Termination Area Plating Material Thickness	2.03 μm[79.92 μin]
Contact Layout	Inline
PCB Contact Termination Area Plating Material Finish	Bright
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Bright
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.5 mm[.02 in]
Termination Post & Tail Length	3.4 mm[.134 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Retention Solder Tails
Mating Retention Type	Locking
Connector Mounting Type	Board Mount
Mating Alignment	
Mating / ingrintent	With
PCB Mount Alignment	With Without
PCB Mount Alignment	Without
PCB Mount Alignment PCB Mount Retention	Without
PCB Mount Alignment PCB Mount Retention Housing Features	Without With
PCB Mount Alignment PCB Mount Retention Housing Features Housing Material	Without With Thermoplastic
PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch)	Without With Thermoplastic
PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch)	Without With Thermoplastic 2 mm[.079 in]
PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length	WithoutWithThermoplastic2 mm[.079 in]20 mm[.787 in]

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Usage Conditions	
Operating Temperature Range	-25 – 85 °C[-13 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	300
Packaging Type	Bag
Product Compliance	
For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022

#### (223)

Does not contain REACH SVHC

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Halogen Content

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

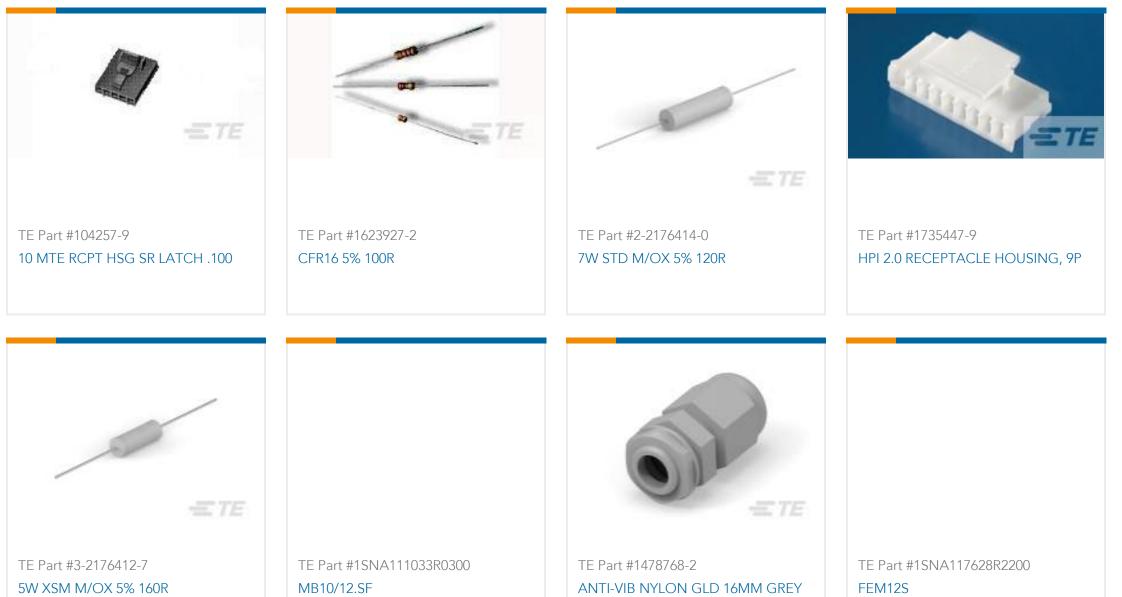
# **Compatible Parts**

PCB Mount Header, Vertical, Wire-to-Board, 9 Position, 2 mm [.079 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, Signal, Natural





# Customers Also Bought



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# Documents

**Product Drawings** 2MM PITCH HPI POST HEADER, VERTICAL, 9P

English

## **CAD** Files

**Customer View Model** ENG\_CVM\_CVM\_1735446-9\_C.2d\_dxf.zip

English

#### 3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1735446-9\_C.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1735446-9\_C.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

PCB Mount Header, Vertical, Wire-to-Board, 9 Position, 2 mm [.079 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, Signal, Natural



Datasheets & Catalog Pages HPI Connectors QRG

English

Product Specifications Application Specification

English